

FEATURES

- Available as "HR" (high reliability) screened per MIL-PRF-19500, JANTX level. Add "HR" suffix to base part number.
- Available as non-RoHS (Sn/Pb plating), standard, and as RoHS by adding "-PBF" suffix.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak repetitive off-state voltage⁽¹⁾ (T _J = -40 to +110°C, sine wave, 50 to 60Hz, gate open)			
MCR72-1		25	
MCR72-2		50	
MCR72-3	V _{DRM}	100	V
MCR72-4	V _{RRM}	200	
MCR72-5		300	
MCR72-6		400	
MCR72-7		500	
MCR72-8		600	
On-state RMS current (180° conduction angles, T _C = 83°C)	I _{T(RMS)}	8.0	A
Peak non-repetitive surge current (half-cycle, sine wave, 60Hz, T _J = 110°C)	I _{TSM}	100	A
Circuit fusing consideration (t = 8.3ms)	I ² t	40	A ² s
Forward peak gate voltage (t ≤ 10μs, T _C = 83°C)	V _{GM}	±5.0	V
Forward peak gate current (t ≤ 10μs, T _C = 83°C)	I _{GM}	1.0	A
Forward peak gate power (pulse width ≤ 10μs, T _C = 83°C)	P _{GM}	5.0	W
Average gate power (t = 8.3ms, T _C = 83°C)	P _{G(AV)}	0.75	W
Operating junction temperature range	T _J	-40 to +110	°C
Storage temperature range	T _{stg}	-40 to +150	°C
Mounting torque	-	8.0	In. lb.

Note 1: V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Maximum	Unit
Thermal resistance, junction to case	R _{θJC}	2.2	°C/W
Thermal resistance, junction to ambient	R _{θJA}	60	°C/W
Lead solder temperature (lead length 1/8" from case, 10s max)	T _L	260	°C

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Peak forward or reverse blocking current⁽²⁾ ($V_{AK} = \text{Rated } V_{DRM} \text{ or } V_{RRM}, R_{GK} = 1\text{k}\Omega$) $T_C = 25^\circ\text{C}$ $T_C = 110^\circ\text{C}$	I_{DRM} I_{RRM}	- -	- -	10 500	μA
ON CHARACTERISTICS					
Peak forward on-state voltage ($I_{TM} = 16\text{A}$, pulse width $\leq 1\text{ms}$, duty cycle $\leq 2\%$)	V_{TM}	-	1.7	2.0	V
Gate trigger current (continuous dc)⁽³⁾ ($V_D = 12\text{V}$, $R_L = 100\Omega$)	I_{GT}	-	30	200	μA
Gate trigger voltage (continuous dc)⁽³⁾ ($V_D = 12\text{V}$, $R_L = 100\Omega$)	V_{GT}	-	0.5	1.5	V
Gate non-trigger voltage ($V_D = 12\text{V}$, $R_L = 100\Omega$, $T_J = 110^\circ\text{C}$)	V_{GD}	0.1	-	-	V
Holding current ($V_D = 12\text{V}$, gate open, initiating current = 200mA)	I_H	-	-	6.0	mA
Gate controlled turn-on time ($V_D = \text{Rated } V_{DRM}$, $I_{TM} = 16\text{A}$, $I_G = 2\text{mA}$)	t_{gt}	-	1.0	-	μs
DYNAMIC CHARACTERISTICS					
Critical rate of rise of off-state voltage ($V_D = \text{rated } V_{DRM}$, $R_{GK} = 1\text{k}\Omega$, $T_J = 110^\circ\text{C}$, exponential waveform)	dv/dt	-	10	-	$\text{V}/\mu\text{s}$

Note 2: Ratings apply for negative gate voltage or $R_{GK} = 1\text{k}\Omega$. Devices shall not have a positive gate voltage concurrently with a negative voltage on the anode. Devices should not be tested with a constant current source for forward and reverse blocking capability such that the voltage applied exceeds the rated blocking voltage.

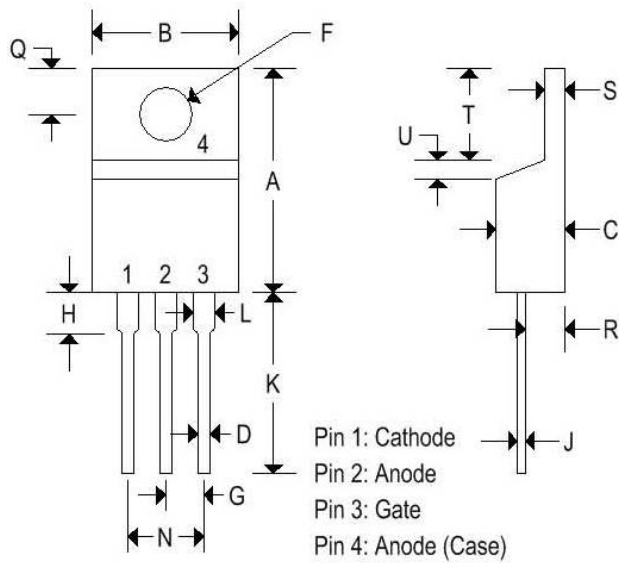
Note 3: R_{GK} current not included in measurement.

MCR72 SERIES

SILICON CONTROLLED RECTIFIERS

MECHANICAL CHARACTERISTICS

Case:	TO-220AB
Marking:	Body painted, alpha-numeric
Pin out:	See below



	TO-220AB			
	Inches		Millimeters	
	Min	Max	Min	Max
A	0.575	0.620	14.600	15.750
B	0.380	0.405	9.650	10.290
C	0.160	0.190	4.060	4.820
D	0.025	0.035	0.640	0.890
F	0.142	0.147	3.610	3.730
G	0.095	0.105	2.410	2.670
H	0.110	0.155	2.790	3.930
J	0.014	0.022	0.360	0.560
K	0.500	0.562	12.700	14.270
L	0.045	0.055	1.140	1.390
N	0.190	0.210	4.830	5.330
Q	0.100	0.120	2.540	3.040
R	0.080	0.110	2.040	2.790
S	0.045	0.055	1.140	1.390
T	0.235	0.255	5.970	6.480
U	-	0.050	-	1.270
V	0.045	-	1.140	-
Z	-	0.080	-	2.030

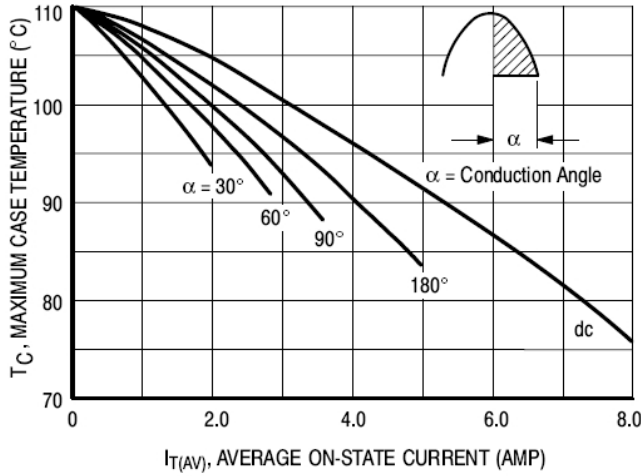


Figure 1. Average Current Derating

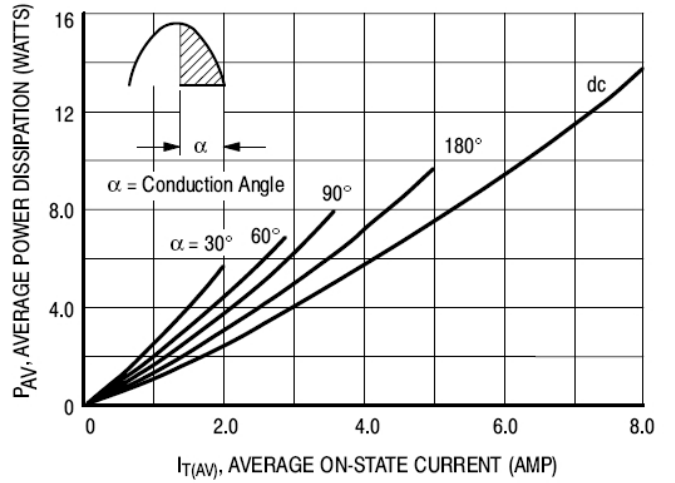


Figure 2. On-State Power Dissipation

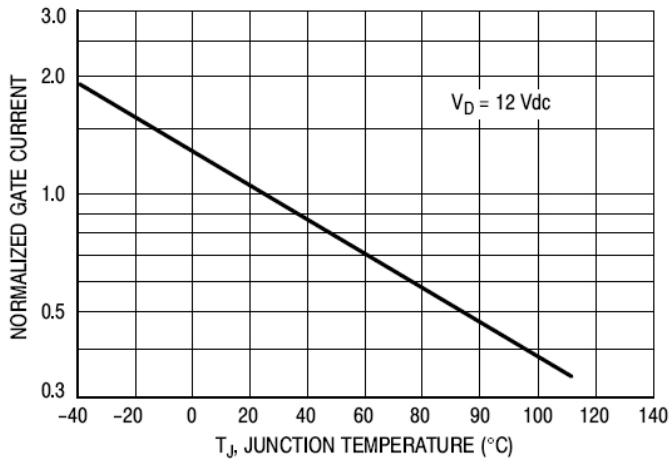


Figure 3. Normalized Gate Current

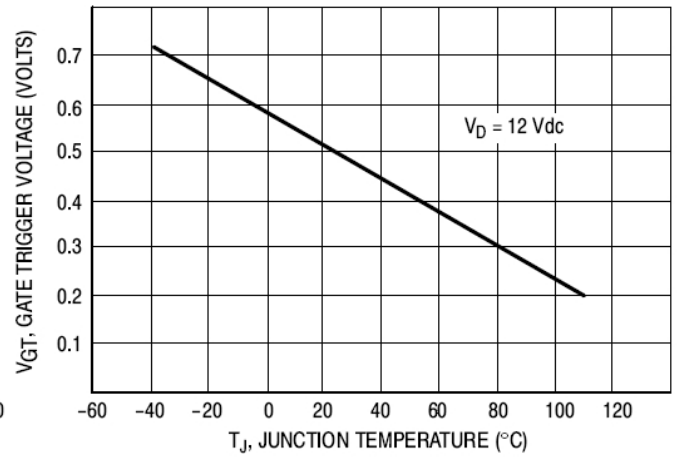


Figure 4. Gate Voltage